

Amendments to Claims

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims

1. (currently amended) A method for forming an apparatus configured to reduce electromagnetic interference between a pair of antennas coupled to a wireless communication device, wherein the method comprises:

extracting a shape of the apparatus from a thin sheet of conductive material; and

folding the shape into a plurality of resonant circuit elements, each configured to resonate at or near a carrier frequency of a signal transmitted by only one of the pair of antennas.

2. (original) The method of claim 1, wherein a process of extracting the shape from the thin sheet of conductive material is selected from a group comprising stamping and laser or chemical etching.

3. (original) The method of claim 2, wherein the conductive material comprises a relative permittivity value of about 0.0 F/m to about 1.0 F/m and a relative permeability value of about 10 H/m to about 100,000 H/m.

4. (original) The method of claim 2, wherein the conductive material comprises a metal selected from a group comprising iron (Fe), copper (Cu), gold (Au), silver (Ag), tin (Sn), and nickel (Ni), or a metal alloy selected from a group comprising beryllium copper (BeCu), phosphor bronze (Ph+Cu/Zn/Sn), magnesium alloys (Mg/Al/O) and steel (Fe/C).

5. (original) The method of claim 2, wherein the conductive material comprises a primarily ferrous-based material.

6. (original) The method of claim 1, wherein the plurality of resonant circuit elements comprise a plurality of rectangular elements connected to and arranged above a common reference plane by a plurality of vertical segments, wherein the plurality of rectangular elements and the common reference plane comprise capacitive portions, and the plurality of vertical segments comprise inductive portions, of the plurality of resonant circuit elements.

7. (original) The method of claim 6, wherein the method further comprises arranging a dielectric material between the plurality of rectangular elements and the common reference plane.

8. (original) The method of claim 1, wherein the plurality of resonant circuit elements comprise a plurality of A-shaped elements separated by a plurality of horizontal segments, wherein flat surfaces of the A-shaped elements comprise capacitive portions, and bent portions of the A-shaped elements comprise inductive portions, of the plurality of resonant circuit elements.

9. (original) The method of claim 1, wherein the plurality of resonant circuit elements comprise a plurality of relatively long domed elements spaced apart by a plurality of relatively thin slots, and wherein the slots comprise capacitive portions, and the domed elements comprise inductive portions, of the plurality of resonant circuit elements.

10. - 23. (canceled)